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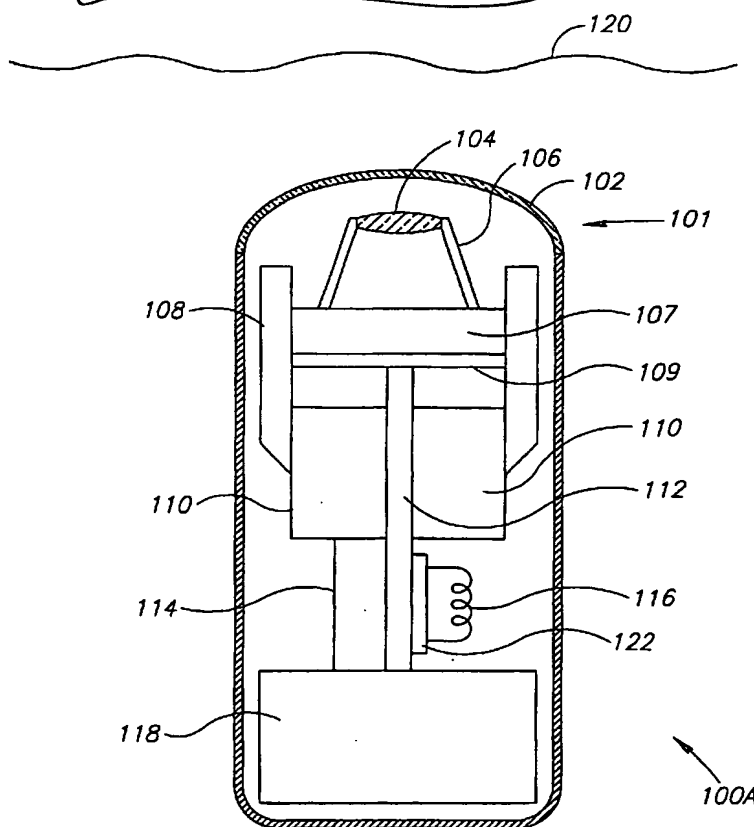
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(54) Title: **REDUCED SIZE IMAGING DEVICE**(57) Abstract: A reduced diameter in vivo
imaging device, such as a swallowable imaging
capsule. The imaging device includes a first
circuit board configured for accommodating
at least an image sensor, and a second circuit
board, which is in electrical communication
with the first circuit board and which extends
substantially perpendicularly from the bottom
surface of the first circuit board.

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